

VERSION WITH MARKINGS TO SHOW CHANGES MADE

- | | | |
|---|-----|-------------|
| 1 | 1. | (Cancelled) |
| 1 | 2. | (Cancelled) |
| 1 | 3. | (Cancelled) |
| 1 | 4. | (Cancelled) |
| 1 | 5. | (Cancelled) |
| 1 | 6. | (Cancelled) |
| 1 | 7. | (Cancelled) |
| 1 | 8. | (Cancelled) |
| 1 | 9. | (Cancelled) |
| 1 | 10. | (Cancelled) |
| 1 | 11. | (Cancelled) |
| 1 | 12. | (Cancelled) |
| 1 | 13. | (Cancelled) |
| 1 | 14. | (Cancelled) |
| 1 | 15. | (Cancelled) |
| 1 | 16. | (Cancelled) |
| 1 | 17. | (Cancelled) |
| 1 | 18. | (Cancelled) |
| 1 | 19. | (Cancelled) |
| 1 | 20. | (Cancelled) |
| 1 | 21. | (Cancelled) |

1 22. (Cancelled)

1 23. (Cancelled)

1 24. (Cancelled)

1 25. (Cancelled)

1 26. (Cancelled)

1 27. (Cancelled)

1 28. (Cancelled)

1 29. (Cancelled)

1 30. (Cancelled)

1 31. (New) An integrated circuit package comprising:

2 a substrate;

3 an integrated circuit attached to the substrate;

4 a first material dispensed at a first temperature between the substrate and the integrated

5 circuit as underfill; and

6 a second material dispensed at a second temperature less than the first temperature

7 around edges of the integrated circuit and the first material to act as a circumferential fillet, the

8 second material having a lower adhesion property than the first material.

1 32. (New) The integrated circuit of claim 31, wherein the second material is an

2 anhydride epoxy.

1 33. (New) The integrated circuit of claim 31, wherein the substrate is baked at a

2 temperature greater than a temperature at which the first and second materials are applied.

1 34. (New) The integrated circuit of claim 31, wherein the second material seals the
2 first material.

1 35. (New) The integrated circuit of claim 31, wherein the second temperature is
2 within a range of 80 degrees Celsius to 120 degrees Celsius.

1 36. (New) The integrated circuit of claim 31, wherein the second material being
2 dispensed only after the first material is dispensed and the integrated circuit is heated to a third
3 temperature being greater than the first temperature.

1 37. (New) An integrated circuit package comprising:
2 a substrate having a first surface and a second surface;
3 an integrated circuit coupled to the first surface of the substrate;
4 a first material coupled to the integrated circuit and the first surface of the substrate, the
5 first material operating as underfill between the integrated circuit and the first surface of the
6 substrate; and
7 a second material attached to the integrated circuit and the first surface of the substrate,
8 the second material forming a circumferential fillet surrounding both edges of the integrated
9 circuit and the first material.

1 38. (New) The integrated circuit package of claim 37, wherein the substrate to
2 electrically connect solder balls on the first surface to solder balls on the second surface.

1 39. (New) The integrated circuit package of claim 37, wherein the first material is
2 dispensed at a temperature within a first temperature range.

1 40. (New) The integrated circuit package of claim 39, wherein the first material
2 being positioned for coupling to the integrated circuit and the first surface of the substrate under
3 a wicking action.

1 41. (New) The integrated circuit package of claim 39, wherein the second material is
2 dispensed at a temperature within a second temperature range having an average temperature less
3 than an average temperature associated with the first temperature range.

1 42. (New) The integrated circuit package of claim 41, wherein the average
2 temperature of the second temperature range is at least ten degrees Celsius less than the average
3 temperature of the first temperature range.

1 43. (New) A printed circuit board comprising:
2 a plurality of solder balls; and
3 an integrated circuit package coupled to the plurality of solder balls, the integrated circuit
4 package comprises

5 a substrate including a first surface and a second surface,
6 an integrated circuit coupled to the first surface of the substrate,
7 a first material coupled to the integrated circuit and the first surface of the
8 substrate, the first material operating as underfill between the integrated circuit and the
9 first surface of the substrate, and

10 a second material attached to the integrated circuit and the first surface of the
11 substrate, the second material forming a circumferential fillet surrounding both edges of
12 the integrated circuit and the first material.

1 44. (New) The printed circuit board of claim 43, wherein the substrate to electrically
2 connect solder balls on the first surface to solder balls on the second surface.

1 45. (New) The printed circuit board of claim 43, wherein first material is dispensed
2 at a temperature within a first temperature range.

1 46. (New) The printed circuit board of claim 43, wherein the first material being
2 positioned for coupling to the integrated circuit and the first surface of the substrate under a
3 wicking action.

1 47. (New) The printed circuit board of claim 43, wherein the second material is
2 dispensed at a temperature within a second temperature range having an average temperature less
3 than an average temperature associated with the first temperature range.

1 48. (New) The printed circuit board of claim 47, wherein the average temperature of
2 the second temperature range is at least ten degrees Celsius less than the average temperature of
3 the first temperature range.

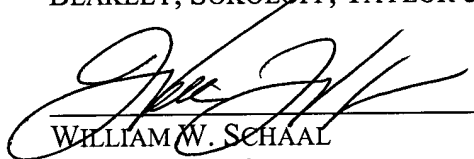
CONCLUSION

In view of the amendments and remarks made above, it is respectfully submitted that all pending claims are in condition for allowance, and such action is respectfully solicited.

Respectfully submitted,

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